

MICROETCHING SOLUTION FOR COPPER, REPLENISHMENT SOLUTION
THEREFOR AND METHOD FOR PRODUCTION OF WIRING BOARD

ABSTRACT

5

Disclosed is a microetching solution for copper, a replenishment solution therefor and a method for production of a wiring board. The microetching solution of the present invention consists of an aqueous solution containing a cupric ion, an organic acid, a halide ion, an amino group-containing compound having a molecular weight of 17 to 400 and a polymer. The polymer is a water-soluble polymer including a polyamine chain and/or a cationic group and having a weight average molecular weight of 1000 or more. When a concentration of the amino group-containing compound is A% by weight and a concentration of the polymer is B% by weight, a value of A/B of the microetching solution of the present invention is 50 to 6000. According to the present invention, an adhesion between copper and a resin or the like may be maintained even with a low etching amount.

10

15

[Fig. 4]